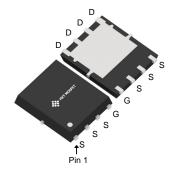


General Description

The BSC100N10NSFG use advanced SGT MOSFET technology to provide low RDS(ON), low gate charge, fast switching and excellent avalanche characteristics.

This device is specially designed to get better ruggedness.

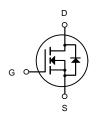


DFN5X6-8L

General Features

 $V_{DS} = 100V I_{D} = 75A$

 $R_{DS(ON)} < 7.5 m\Omega V_{GS} = 10 V$



N-Channel MOSFET

Applications

Consumer electronic power supply Motor control

Synchronous-rectification Isolated DC

Synchronous-rectification applications

Package Marking and Ordering Information

| Product ID | Pack | Brand | Qty(PCS) | |
|---------------|-----------|------------|----------|--|
| BSC100N10NSFG | DFN5X6-8L | HXY MOSFET | 5000 | |

Absolute Maximum Ratings at T_j=25°C unless otherwise noted

| Parameter | Symbol | Value | Unit |
|--|----------------|------------|------|
| Drain source voltage | VDS | 100 | V |
| Gate source voltage | VGS | ±20 | V |
| Continuous drain current ¹⁾ | ID | 75 | А |
| Pulsed drain current ²⁾ | ID, pulse | 300 | А |
| Power dissipation ³⁾ | P _D | 97 | W |
| Single pulsed avalanche energy ⁵⁾ | EAS | 90 | mJ |
| Operation and storage temperature | Tstg,Tj | -55 to 150 | °C |
| Thermal resistance, junction-case | RθJC | 1.3 | °C/W |



Electrical Characteristics (T_J=25°C unless otherwise specified)

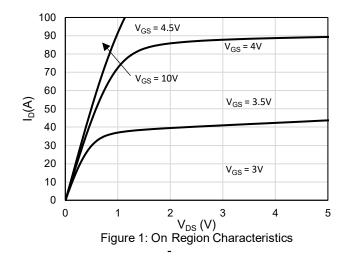
| Symbol | Parameter | Test Condition | Min. | Тур. | Max. | Units |
|----------------------|--|--|------|------|------|-------|
| Off Charac | cteristic | | | | | |
| V _{(BR)DSS} | Drain-Source Breakdown Voltage | V _{GS} =0V, I _D =250μA | 100 | - | - | V |
| I _{DSS} | Zero Gate Voltage Drain Current | V _{DS} =100V, V _{GS} =0V, | - | - | 1.0 | μA |
| I _{GSS} | Gate to Body Leakage Current | V _{DS} =0V, V _{GS} = ±20V | - | - | ±100 | nA |
| On Charac | cteristics | | ı | l | I | |
| V _{GS(th)} | Gate Threshold Voltage | V _{DS} =V _{GS} , I _D =250μA | 1.0 | 1.6 | 2.5 | V |
| | Static Drain-Source on-Resistance | V _{GS} =10V, I _D =20A | - | 6.4 | 7.5 | mΩ |
| $R_{DS(on)}$ | note3 | V _{GS} =4.5V, I _D =8A | - | 9.2 | 11.4 | mΩ |
| Dynamic (| Characteristics | | • | • | | |
| C _{iss} | Input Capacitance | | - | 2944 | - | pF |
| Coss | Output Capacitance | V _{DS} =50V, V _{GS} =0V, | - | 736 | - | pF |
| C _{rss} | Reverse Transfer Capacitance | f=1.0MHz | - | 2.04 | - | pF |
| Qg | Total Gate Charge | V _{DS} =50V, I _D =30A, | - | 39.4 | - | nc |
| Q _{gs} | Gate-Source Charge | | - | 5.6 | - | nc |
| Q_{gd} | Gate-Drain("Miller") Charge | V _{GS} =10V | - | 7.6 | - | nc |
| Switching | Characteristics | | | | | |
| t _{d(on)} | Turn-on Delay Time | | _ | 13 | - | nc |
| t _r | Turn-on Rise Time | V _{DD} =50V, I _D =25A, | - | 27.5 | - | nc |
| t _{d(off)} | Turn-off Delay Time | R _G =6Ω, V _{GS} =10V | _ | 45.5 | - | nc |
| t _f | Turn-off Fall Time | | - | 41.5 | - | nc |
| Drain-Sou | rce Diode Characteristics and Maxim | um Ratings | | | | |
| Is | Maximum Continuous Drain to Source Diode Forward Current | | | - | 75 | А |
| I _{SM} | Maximum Pulsed Drain to Source Diode Forward Current | | - | - | 300 | Α |
| V_{SD} | Drain to Source Diode Forward Voltage | V _{GS} =0V, I _S =30A | - | - | 1 | V |
| t _{rr} | Body Diode Reverse Recovery Time | T.=25°C | - | 177 | - | ns |
| Qrr | Body Diode Reverse Recovery Charge | T _J =25°C, I _F =12A,dI/dt=100A/μs | - | 1291 | - | nc |

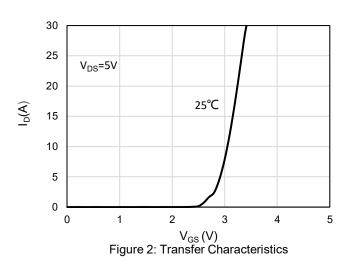
Notes:1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature

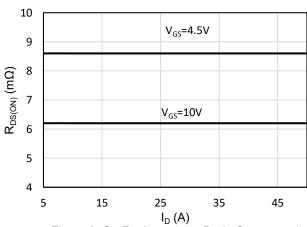
- 2. EAS condition: T_J =25°C, V_{DD} =50V, V_G =10V, R_G =25 Ω , L=0.5mH, I_{AS} =19A
- 3. Pulse Test: Pulse Width≤300µs, Duty Cycle≤0.5%

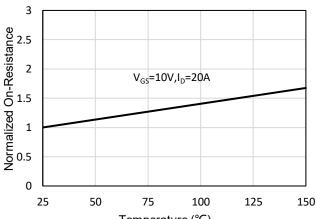


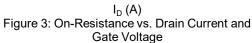
Typical Performance Characteristics

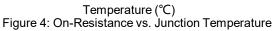


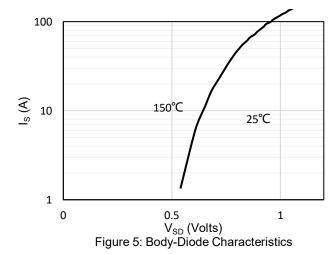


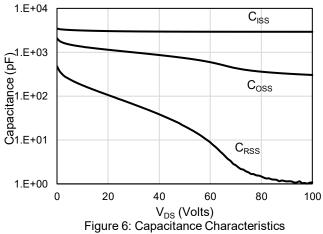




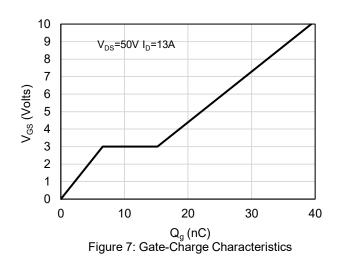


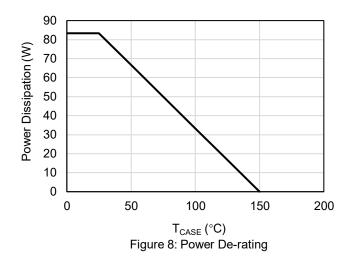


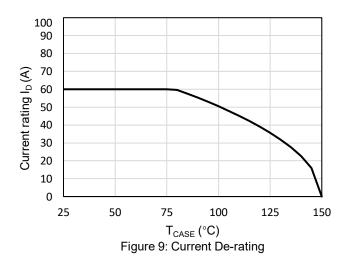


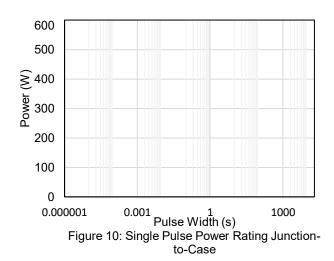


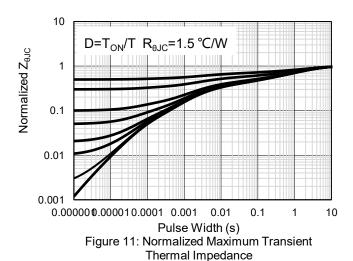












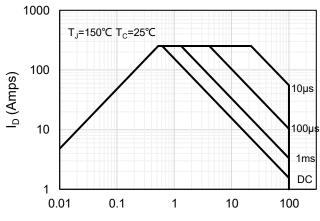
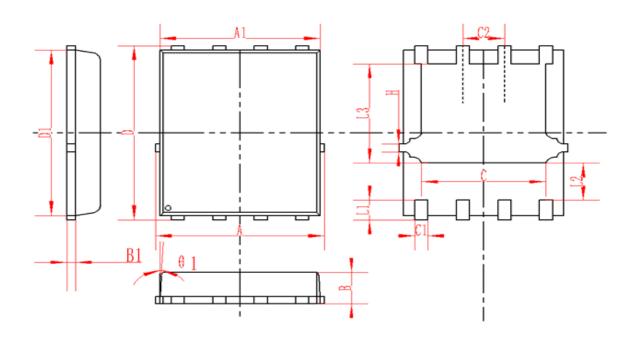


Figure 12: Maximum Forward Biased Safe Operating Area

DFN5X6-8L Package Information



| SYMBOL | MM | | INCH | | | |
|--------|----------|------|----------|-------|-------|-------|
| | MIN | NOM | MAX | MIN | NOM | MAX |
| А | 4.95 | 5 | 5.05 | 0.195 | 0.197 | 0.199 |
| A1 | 4.82 | 4.9 | 4.98 | 0.190 | 0.193 | 0.196 |
| D | 5.98 | 6 | 6.02 | 0.235 | 0.236 | 0.237 |
| D1 | 5.67 | 5.75 | 5.83 | 0.223 | 0.226 | 0.230 |
| В | 0.9 | 0.95 | 1 | 0.035 | 0.037 | 0.039 |
| B1 | 0.254REF | | 0.010REF | | | |
| С | 3.95 | 4 | 4.05 | 0.156 | 0.157 | 0.159 |
| C1 | 0.35 | 0.4 | 0.45 | 0.014 | 0.016 | 0.018 |
| C2 | 1.27TYP | | 0.5TYP | | | |
| θ1 | 8° | 10° | 12° | 8° | 10° | 12° |
| L1 | 0.63 | 0.64 | 0.65 | 0.025 | 0.025 | 0.026 |
| L2 | 1.2 | 1.3 | 1.4 | 0.047 | 0.051 | 0.055 |
| L3 | 3.415 | 3.42 | 3.425 | 0.134 | 0.135 | 0.135 |
| Н | 0.24 | 0.25 | 0.26 | 0.009 | 0.010 | 0.010 |



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